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ANSWER 2 OF 3 CA COPYRIGHT 2005 ACS on STN
1.9
     127:142368 CA
.AN
     Entered STN: 02 Sep 1997
ED
     Ion beam intermixing of semiconductor heterostructures for optoelectronic
TΙ
     applications
AU
     Goldberg, R. D.; Mitchell, I. V.; Poole, P.; Labrie, D.; Lafontaine, H.;
     Aers, G. C.; Williams, R.; Dion, M.; Charbonneau, S.; Ramanujancha, K.;
     Weatherly, G. C.
     Department of Physics, The University of Western Ontario, London, Ontario,
CS
     Can.
SO
     Nuclear Instruments & Methods in Physics Research, Section B: Beam
     Interactions with Materials and Atoms (1997), 127/128, 418-422
     CODEN: NIMBEU; ISSN: 0168-583X
PB
     Elsevier
DΤ
     Journal
LA
     English
CC
     73-10 (Optical, Electron, and Mass Spectroscopy and Other Related
     Properties)
     Section cross-reference(s): 76
     The ability of radiation enhanced quantum well (QW) intermixing to produce
AB
     active integrated photonic devices was demonstrated by the manufacture of a set
    of wavelength tuned lasers from a single semiconductor wafer. Defects,
     created in the InP-based structure by a high energy (1 MeV) P implant,
     enhance the diffusion of atomic species across the as-grown heterojunctions
     during subsequent rapid thermal annealing (90 s at 700°). As a
     result, the QW band gap energy is blue shifted with respect to
     unirradiated regions. It is shown that by implanting through a SiO2 mask
     of varying thickness, the bandgap of the QW can be selectively tailored
     across the wafer. Addnl. results from GaAs- and SiGe-based QW systems are
     presented to illustrate how bandgap engineering techniques may be improved
     through a better understanding of the defect interactions involved. In
     the GaAs-based structure, defect trapping at structural interfaces was
      identified as a possible hindrance to ion assisted intermixing. In
     contrast, data from the group IV QWs highlights the benefits of a low
     temperature (24 h at 630°) anneal prior to irradiation By removing defects
      from the as-grown material with pre-annealing, the
      relative bandgap shift induced by ion bombardment is doubled.
ST
     ion beam intermixing annealing quantum well; semiconductor laser ion beam
      intermixing; band gap tuning ion beam interdiffusion; phosphorus ion beam
      implantation quantum well
IT
     Diffusion
         (interdiffusion; ion beam enhanced quantum well
         intermixing and annealing for band gap blue-shift in
         optoelectronic devices)
TΤ
     Band gap
     Ion implantation
     Quantum well devices
     Rapid thermal annealing
     Semiconductor lasers
         (ion beam enhanced quantum well intermixing
         and annealing for band gap blue-shift in optoelectronic devices)
ΙT
     7440-21-3, Silicon, uses
     RL: DEV (Device component use); USES (Uses)
         (ion beam enhanced quantum well intermixing
         and annealing for band gap blue-shift in optoelectronic devices)
     1303-00-0, Gallium arsenide (GaAs), properties 12623-04-0, Germanium silicide (Ge0.3Si0.7) 22398-80-7, Indium phosphide (InP), properties
ΙT
                                                        12623-04-0, Germanium
     106097-59-0, Gallium indium arsenide (Ga0.47In0.53As)
                                                               109414-09-7,
     Aluminum gallium arsenide (Al0.71Ga0.29As)
                                                   113172-24-0, Gallium indium
     arsenide phosphide (Ga0.26In0.74As0.57P0.43)
                                                      115454-37-0, Gallium indium
     arsenide (Ga0.79In0.21As)
     RL: DEV (Device component use); PEP (Physical, engineering or chemical
      process); PRP (Properties); PROC (Process); USES (Uses)
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(ion beam enhanced quantum well intermixing
         and annealing for band gap blue-shift in optoelectronic devices)
- IT
      7723-14-0, Phosphorus, processes
      RL: PEP (Physical, engineering or chemical process); PROC (Process)
         (ion beam enhanced quantum well intermixing
         for band gap blue-shift)
IT
      7631-86-9, Silicon oxide (SiO2), uses
      RL: NUU (Other use, unclassified); USES (Uses)
         (ion beam enhanced quantum well intermixing
         using silica mask for local band gap tuning)
RE.CNT
               THERE ARE 21 CITED REFERENCES AVAILABLE FOR THIS RECORD
RE
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 L9
      ANSWER 3 OF 3 CA COPYRIGHT 2005 ACS on STN
      126:111557 CA
ΑN
      Entered STN: 18 Feb 1997
 ED
TΙ
      Effect of low-temperature pre-annealing on ion
      implant-assisted intermixing of Sil-xGex/Si quantum wells
ΑU
      Labrie, D.; Aers, G. C.; Lafontaine, H.; Williams, R. L.; Charbonneau, S.;
      Goldberg, R. D.; Mitchell, I. V.
      Inst. Microstructural Sci., Natl. Res. Council, Ottawa, KA1 OR6, Can.
 CS
      Applied Physics Letters (1996), 69(25), 3866-3868
 SO
      CODEN: APPLAB; ISSN: 0003-6951
 PB
      American Institute of Physics
 DΤ
      Journal
 LA
      English
 CC
      76-3 (Electric Phenomena)
      Section cross-reference(s): 73
      By using photoluminescence, the authors have studied the effect of a low
AB
      temperature "pre-anneal" stage on the intermixing of 3-nm Si0.7Ge0.3/Si quantum
     wells implanted with silicon ions having energies up to 1 MeV and then exposed to rapid thermal annealing at 850^{\circ} for 300 s. They find
      that an unwanted quantum well band gap increase in unimplanted samples
      after rapid thermal annealing can be reduced substantially from .apprx.30
      to .apprx.5 meV due to the removal of grown-in defects by pre-
      annealing at 630° for 24 h. Pre-annealed samples that were
      implanted and rapid thermal annealed showed at least the same band gap.
      increase (up to 70 meV in these samples) observed for non-pre-annealed
               These results are understood in terms of significantly different
      activation energies for defect diffusion and quantum
      well intermixing and a nonlinear dependence of the
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energy shifts on defect concns.
ST
     germanium silicon quantum well intermixing;
     luminescence germanium silicon quantum well; annealing ion implantation
     silicon germanium well
     Annealing
IT
     Quantum well devices
        (effect of low-temperature pre-annealing on ion
        implant-assisted intermixing of Sil-xGex/Si quantum wells)
IT
        (of ion implant-assisted intermixed Sil-xGex/Si quantum wells)
                                      12623-04-0, Germanium 30, silicon 70
     7440-21-3, Silicon, properties
IT
     (atomic)
     RL: PRP (Properties)
        (quantum wells; effect of low-temperature pre-annealing
        on ion implant-assisted intermixing of Sil-xGex/Si quantum wells)
              THERE ARE 24 CITED REFERENCES AVAILABLE FOR THIS RECORD
RE.CNT
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(FILE 'HOME' ENTERED AT 12:25:49 ON 31 JAN 2005) FILE 'INSPEC' ENTERED AT 12:26:16 ON 31 JAN 2005 FILE 'INSPEC' ENTERED AT 12:26:43 ON 31 JAN 2005 95 QWI L1L2 342 QUANTUM (A) WELL (A) INTERMIXING L3 367 L1 OR L2 L4314 PRE-ANNEALING OR (PRE(A)ANNEALING) L5116382 DEFECTS L613 L4(20A)L5 0 L3 AND L6 Ĺ7 0 L3 AND L4 L8FILE 'CA' ENTERED AT 12:29:50 ON 31 JAN 2005 3 L8 L9 FILE 'INSPEC' ENTERED AT 12:40:59 ON 31 JAN 2005

WEST Search History

Hide Items Restore Clear Cancel

DATE: Monday, January 31, 2005

Hide?	Set Name		Hit Count
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	L51	L50 and 149	1425
	L50	438/\$.ccls.	161966
	L49	chandra.xp.	1460
	L48	chnadra.xp.	0
	L47	L46 and 11	3
	L46	438/795-799.ccls.	2937
	L45	11 and 144	2
	L44	438/510-532.ccls.	6313
	L43	phosistor\$.asn.	7
	L42	phosistor\$.asn.	7
	L41	12 and 134	2
	L40	139 and 134	1
	L39	L38	576
	L38	mulpuri.xa,xp.	576
	L37	L36 and 135	1
	L36	mulpuri.xp.	351
	L35	L34 and 11	11
	L34	ooi.inv.	1280
	L33	5708674	19
	L32	L31 and 124	27
	L31	L30 same 129 same 127	80987
	L30	chromium or cr	780659
	L29	L28 or l25	691173
	L28	nickel	393779
	L27	cu or copper	1234855
	L26	cu or copper	1234855
	L25	ni or nickle	410173
	L24	121 and 122	654
	L23	L22 and 122	345383
	L22	strain	345383

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	L20	11 and 14	70
\Box .	L19	11 same 114	40
	L18	L17 and 110	2
	L17	patterned adj mask	5932
	L16	patterned adj mask	10
	L15	114 and 113	9
	L14	defects	412202
	L13	l2 and l11	11
	L12	12 and 111L11	0
	L11	quantum adj well	18041
	L10	l2 and l1	6
	L9	L8 and 11	38
	L8	l6 same l4	7034
	L7	L6 and 15	48
	L6	defect\$5	537557
	L5	L4 and 11	70
	L4	\$4annealing or (pre adj annealing)	162734
	L3	L2 and l1	6
	L2	PRE-ANNEAL\$4	920
	L1	qwi or (quantum adj well adj intermix\$5)	138

END OF SEARCH HISTORY